

CLAIM AMENDMENTS

- 1. (Original) A method for producing a polishing pad comprising
- (a) providing a porous polymer structure;
- (b) compressing at least a region of the porous polymer structure to provide a translucent region; and
- (c) forming a polishing pad comprising the porous polymer structure, whereby a polishing pad is produced comprising the translucent region.
- 2. (Original) The method of Claim 1 further comprising heating the porous polymer structure.
- 3. (Original) The method of Claim 2, wherein the porous polymer structure is heated to a temperature within about 50°C of its melting temperature.
- 4. (Original) The method of Claim 3, wherein the porous polymer structure is heated to a temperature about 10-50°C above its melting temperature.
- 5. (Previously Presented) The method of Claim 1, wherein the porous polymer structure is compressed to a thickness that is about 10-50% of its thickness prior to compression.
- 6. (Previously Presented) The method of Claim 5, wherein the porous polymer structure is compressed to a thickness that is about 20-40% of its thickness prior to compression.
- 7. (Original) The method of Claim 1, wherein the porous polymer structure is opaque prior to the compression step.
- 8. (Original) The method of Claim 1, wherein the porous polymer structure comprises a thermoplastic.
- 9. (Original) The method of Claim 8, wherein the porous polymer structure comprises polyurethane.
- 10. (Original) The method of Claim 1 further comprising mating the translucent region to a second polymer structure.

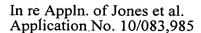


- 11. (Original) The method of Claim 1, wherein the polishing pad further comprises a substantially opaque region.
- 12. (Original) The method of Claim 11, wherein the substantially opaque region is provided by a non-compressed region of the porous polymer structure.
- 13. (Original) The method of Claim 11, wherein the substantially opaque region is provided by a material that is different from the porous polymer structure.
- 14. (Original) The method of Claim 12, wherein the translucent region is thinner than the substantially opaque region.
- 15. (Original) The method of Claim 1, further comprising overlaying the region of the porous polymer structure to be compressed with a space-filling material prior to compressing.
- 16. (Original) The method of Claim 15, wherein the porous polymer structure and space-filling material overlaid thereupon are compressed to a thickness about equal to that of the porous polymer structure prior to compressing.
- 17. (Original) The method of Claim 16, wherein the space-filling material is the same as the porous polymer.
- 18. (Original) The method of Claim 1, wherein the porous polymer structure comprises an intrinsic surface texture.
- 19. (Original) The method of Claim 18, wherein the translucent region comprises an intrinsic surface texture.
- 20. (Original) The method of Claim 1, further comprising providing an extrinsic surface texture on at least a portion of the surface of the polishing pad.
- 21. (Original) The method of Claim 1, wherein the translucent region is translucent to light having a wavelength of about 190-3500 nm.
- 22. (Previously Presented) A polishing pad produced by a method comprising:
 - (a) providing a porous polymer structure;



In re Appln. of Jones et al. Application No. 10/083,985

- (b) compressing a region of the porous polymer structure to provide a translucent region; and
- (c) forming a polishing pad comprising the porous polymer structure, whereby a polishing pad is produced comprising the translucent region.
- 23. (Original) The polishing pad of claim 22, wherein the translucent region is porous.
- 24. (Original) The polishing pad of claim 23, wherein the translucent region is sufficiently porous to absorb or transport polishing slurry.
- 25. (Original) A polishing pad comprising a region that is at least translucent, wherein the translucent region is porous.
- 26. (Original) The polishing pad of claim 25, wherein the translucent region is sufficiently porous to absorb or transport polishing slurry.
- 27. (Original) The polishing pad of claim 26, wherein the polishing pad further comprises a substantially opaque region.
- 28. (Original) The polishing pad of claim 27, wherein the substantially opaque region of the polishing pad is provided by a non-compressed region of the porous polymer structure.
- 29. (Original) The polishing pad of claim 27, wherein the substantially opaque region of the polishing pad is provided by a material that is different from the porous polymer structure.
 - 30. (Previously Presented) A method of polishing a substrate comprising
 - (i) contacting a substrate with a polishing pad produced by a method comprising:
 - (a) providing a porous polymer structure;
 - (b) compressing a region of the porous polymer structure to provide a translucent region; and



- (c) forming a polishing pad comprising the porous polymer structure, whereby a polishing pad is produced comprising the translucent region, and
- (ii) moving the substrate and polishing pad relative to each other.
- 31. (Original) The method of Claim 30, wherein the substrate is a semiconductor device.
- 32. (Original) The method of Claim 31 further comprising passing light through the translucent region of the polishing pad to evaluate the polishing of the substrate.
 - 33. (Original) The method of Claim 32, wherein the light is a laser light.
- 34. (Previously Presented) A method of polishing a substrate comprising (i) contacting a substrate with a polishing pad comprising a region that is at least translucent, wherein the translucent region is porous, and (ii) moving the substrate and polishing pad relative to each other.
- 35. (Original) The method of Claim 34, wherein the substrate is a semiconductor device.
- 36. (Original) The method of Claim 35, further comprising passing light through the translucent region of the polishing pad to evaluate the polishing of the substrate.
 - 37. (Original) The method of Claim 36, wherein the light is a laser light.

